

ABSTRACT

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10 A probe card having multiple planes with continuous metal traces from a high density of small, robust probe contacts to peripheral vias which enable connection to a test head is fabricated using technology from the printed circuit card industry. The card includes a relatively small, centrally located recessed plane having a plurality of probe contacts precisely patterned to mate with chip contacts, an array of continuous conductive traces, the substrate is folded at specific crease locations, and formed upward to a second array of creases at which the substrate is bent to form a raised plane parallel to the first.

15 Integrated single unit construction, coupled with adaptability for rapid pattern design or changes in conductors readily enables a low inductance probe card, and its low cost, automated method of manufacture is compatible with tight pitch and high performance requirements of integrated circuits both in current production, and those in
20 plans for the future.